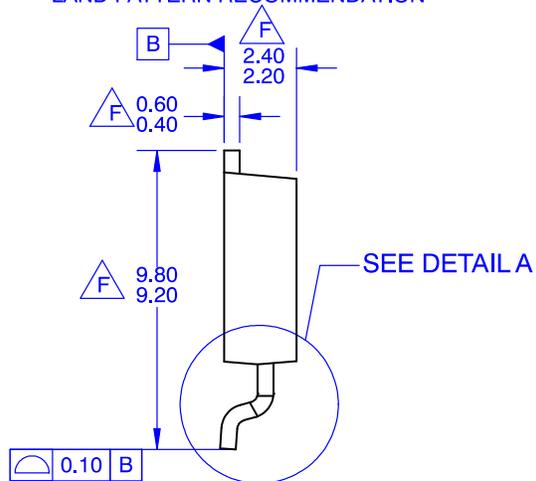
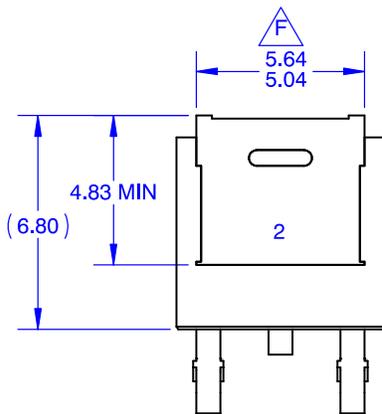
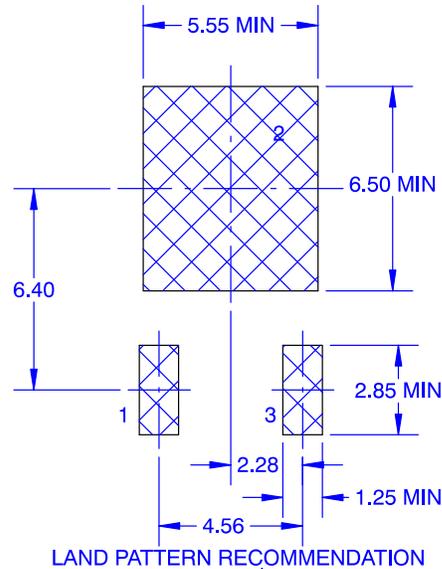
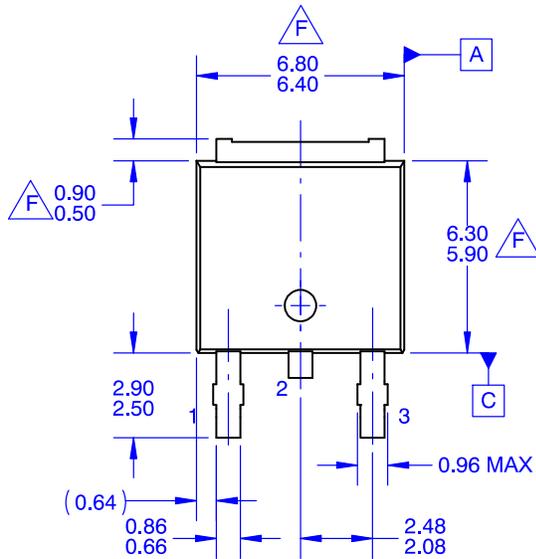


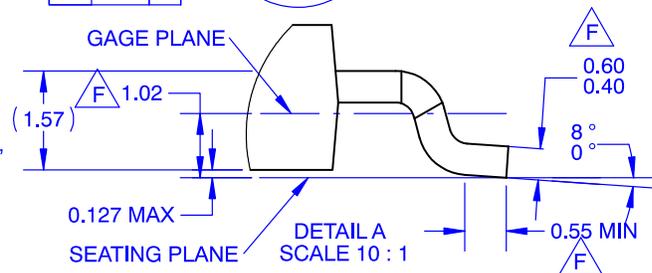
**DPAK3**  
**CASE 369AK**  
**ISSUE O**

DATE 30 SEP 2016



**NOTES: UNLESS OTHERWISE SPECIFIED**

- A) NOT COMPLIANT TO JEDEC TO-252 VARIATION AB
- B) ALL DIMENSION ARE IN MILLIMETER
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- D) LAND PATTERN PER IPC7351A STANDARD TO228P991X239-3N
- E) DOES NOT COMPLY TO JEDEC STANDARD VALUE.



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<b>DESCRIPTION:</b> DPAK3	<b>PAGE 1 OF 1</b>

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